

IN THE CLAIMS:

1. (Currently Amended) An LED mounting module, comprising:

a substrate; and

a plurality of reflecting member members each made of a resin material and having a reflecting hole in a position corresponding to ~~an LED device which is~~ one of LED

- 5 devices which are to be mounted on one of main surfaces of the substrate, wherein

the substrate and the reflecting ~~member members~~ are directly adhered to each other in such a state that the main surface of the substrate is in contact with one of main surfaces of the reflecting ~~member members~~, and

the reflecting members are each a separate unit.

2. (Original) The LED mounting module of Claim 1, wherein

the substrate includes an insulation board made of a resin material, and a wiring pattern on one of main surfaces of the insulation board, and

the resin material forming the insulation board contains a same resin as the resin
5 material forming the reflecting member.

3. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermosetting resin material principally containing an epoxy resin.

4. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermoplastic resin material principally containing a resin selected from a group consisting of a polyphthalamide resin, a liquid crystal polymer, a polyphenylene sulfide resin, and a polybutylene terephthalate resin.

5. (Original) The LED mounting module of Claim 1, wherein
the resin material contains one or more fillers to improve reflection efficiency.
6. (Currently Amended) The LED mounting module of Claim 5, wherein
the fillers include at least one of ~~TiO₂, SiO₂, Al₂O₃, and BaSO₄~~ TiO₂, SiO₂, Al₂O₃, and BaSO₄.
7. (Currently Amended) The LED mounting module of Claim 2, wherein
the resin material forming the insulation board contains at least one of ~~Al₂O₃, AlN, SiO₂~~ Al₂O₃, AlN, SiO₂, and SiC.
8. (Original) The LED mounting module of Claim 2, wherein
a metal board is provided on the other main surface of the substrate, and
the resin material forming the insulation board is a composite material containing an inorganic filler and a thermosetting resin material.
9. (Original) The LED mounting module of Claim 2, wherein
a metal board is provided on the other main surface of the substrate, and
the resin material forming the insulation board is a thermosetting resin material containing a glass fiber.

10. (Original) The LED mounting module of Claim 1, wherein
a depression is formed in a part of the substrate at which the reflecting member is
adhered, and

the depression is filled with the resin material forming the reflecting member.

11. (Original) The LED mounting module of Claim 1, wherein
the LED device is one of a plurality of LED devices that are to be mounted on the
main surface of the substrate, and

the reflecting hole is one of a plurality of reflecting holes formed in the reflecting
5 member in correspondence with the plurality of LED devices.

12. (Original) The LED mounting module of Claim 1, wherein
the substrate includes an insulation board made of a ceramic material, and a
wiring pattern on one of main surfaces of the insulation board.

13. (Currently Amended) The LED mounting module of Claim 12, wherein
the ceramic material contains at least one of Al_2O_3 , Al_2O_3 , AlN , SiO_2 , SiO_2 , and
SiC.

14. (Original) An LED module comprising:
the LED mounting module defined in Claim 1; and
an LED device mounted on the LED mounting module.

15.-27. (Cancelled)